





DESCRIPTION

Subminiature size, easily solderable or weldable planar ribbon leads and high performance design makes the FP transformer ideal for MIC substrate and printed circuits.

These transformers are high reliability devices designed to meet MIL-T-55631. Typical applications are: Interstage coupling, phase detection, DC decoupling, voltage/current step up/step down and pulse transformation.

GUARANTEED MINIMUM PERFORMANCE DATA

SPECIFICATIONS FOR MODEL FP-528

Type: 50 ohm unbalanced 200 ohm balanced DC isolated C.T.

- 1 dB Bandwidt	h, MHz	1-250
Midband insertion loss dB		.75
Amplitude unbalance dB		1.0
Phase unbalance	•	
(deviation from 180°)°		12
VSWR	1-50 MHz	1.3:1
	50-250 MHz	2.5:1

NOTE:

- 1 dB bandwidth is measured relative to midband loss.

ABSOLUTE MAXIMUM RATINGS:

Input power *1 w. above 10 MHz, .25 w. below 10 MHz
Temperature range -54° to +100°C

*Includes DC current effects by approx. (IDC2 + IRF2)Z \cong Pmax.

ENVIRONMENTAL CONDITIONS

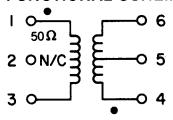
GUARANTEED ENVIRONMENTAL PERFORMANCE:

All units are designed to meet their specifications over - 54°C to + 100°C and after exposure to any or all of the following tests per

WIIL-OID-202L.		Test
Exposure	Method	Condition
Thermal Shock	107D	В
Altitude	105C	G
H.F. Vibration	204C	D
Mechanical Shock	213B	С
Random Vibration	214	IIF
(15 minutes per axis)		
Solderability	208C	
Terminal Strength	211A	С
Resistance to		
Soldering Heat	210A	В

Sealed units, meet the requirements of Method 106D of MIL-STD-202E when exposed to humidity.

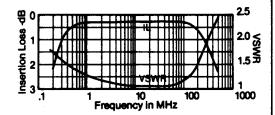
FUNCTIONAL SCHEMATIC



TYPICAL PERFORMANCE

FP-528

Risetime: .3 nS Droop: (10%) 250 nS Group delay: <1 nS

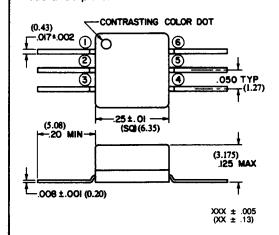


PACKAGE MATERIAL:

Header: Glass filled epoxy Leads: Kovar per MIL-STD-1276, Type K

FINISH:

Header: Black epoxy Leads: Hot dipped solder, tin lead underplate.



Specifications subject to change without notice.

8.10.04 Rev. A